

catalog

01	Cover sheet	43	GFX Switch
02	Block_Diagram	44	GPU Power Sequence
03	SMBUS & Reset Topology	45	GPU PCIE Gen2x16 Interface
04	Power_On_Sequence	46	GPU Frame Buffer Interface
05	Power_Block	47	GPU Memory Partition Part1
06	Clock Generator	48	GPU Memory Partition Part2
07	CPU1 DMI & FDI & X16_PEG	49	GPU Memory Partition Part3
08	CPU2 DDR3 A & B	50	GPU Memory Partition Part4
09	CPU3 RSVD & VSS	51	GPU FBVDD/Q Decoupling
10	CPU4 POWER1	52	GPU NVVDD Decoupling
11	CPU5 POWER2	53	GPU IFPA/B/C LVDS & HDMI
12	THERMAL & CPU FAN	54	GPU IFPD/EF DAC-VGA
13	DDR3 SODIMM0	55	GPU MIOA/B & Straps
14	DDR3 SODIMM1	56	GPU Thermal Sensor & GPIOs
15	PCH1 HDA & SPI & SATA	57	GPU Power NVVDD
16	PCH2 PCIE & SMBUS & CLK	58	GPU Power FBVDD&Q
17	PCH3 DMI & FDI & VGA & LVDS & DDI	59	GPU Power Rails
18	PCH4 PCI & USB & NVRAM	60	GPU Powers Discharge
19	PCH5 GPIOs & RSVD & VSS	61	GPU Ventura Platform
20	PCH6 POWER1	62	DCIN & USB Board
21	PCH7 POWER2	63	Platform Change List
22	LCD Connector		
23	CRT Connector		
24	HDMI Port		
25	PCIE LAN		
26	Audio_ALC662		
27	Audio Jack		
28	Card Reader		
29	MiniCard1-WIFI		
30	3G Card Connector & Powergoods		
31	Camera & Blue Tooth		
32	USB Port & LED & ME Holes		
33	SATA Connector & Keyboard Connector		
34	KBC-IT8502E-NX		
35	Small Board Connectors		
36	Power_Charger & Battery Connector		
37	Power_System +V5A-3.3A-1.5A		
38	Power_+V1.5M_+V0.75M-1.8S		
39	Power_+V1.05S & +V1.05S_VTT		
40	Power_VCCSA		
41	Power_VCCCore & GFX Core		
42	Power_S3_S4 & Discharge		


INTEL Chief River Platform

Version : A
Drawing by : Wain

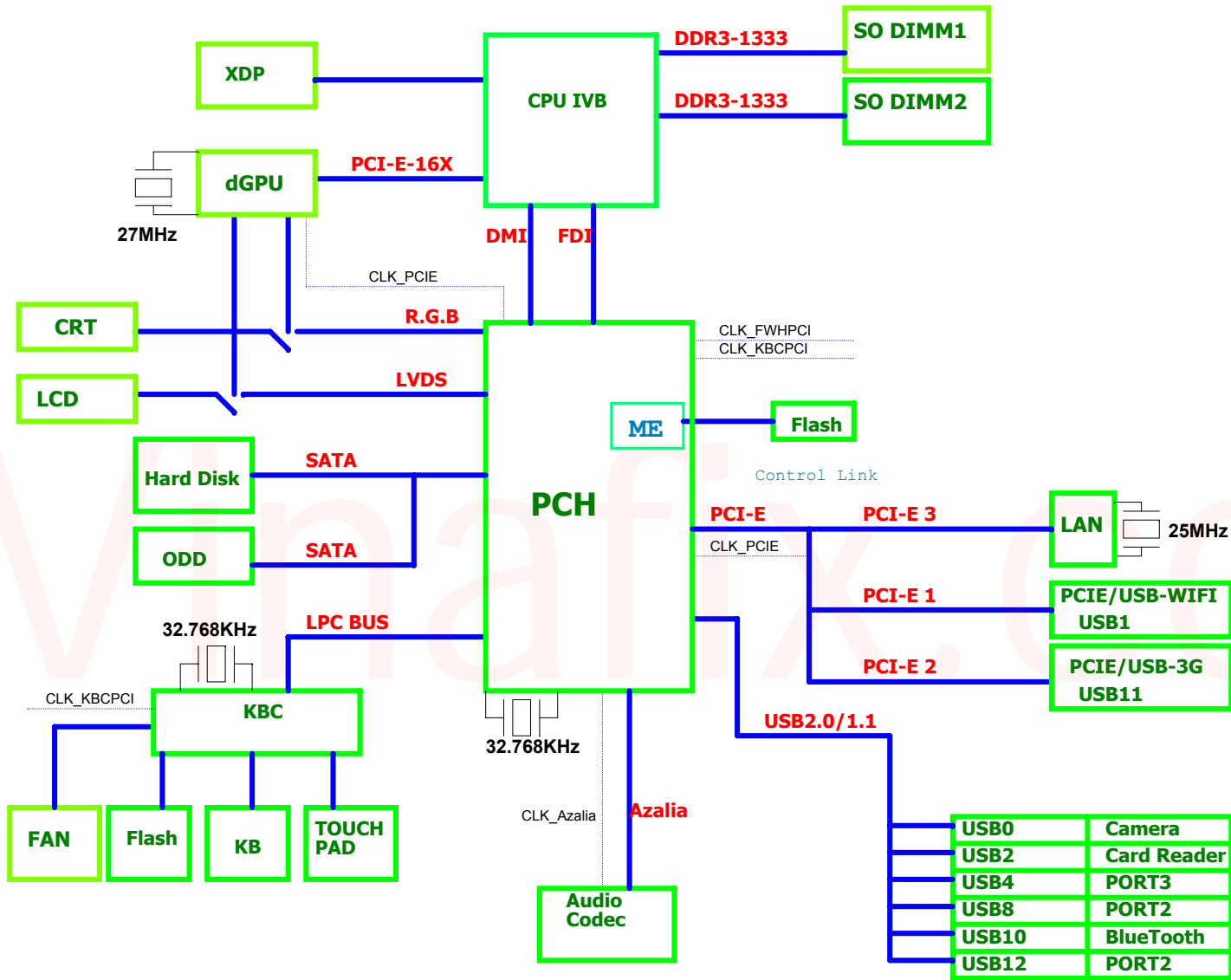
Notes:

Part Value Prefix : "@" means nopop
Net Value suffix : "#" means Low Active

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Title <Title>		Rev A	
Size C	Sheet Name	Cover Sheet	
ENGINEER:	Wain	Date:	Thursday, March 21, 2013
		Sheet	1 of 38

X300DE/X300V/X300 BLOCK DIAGRAM



System Power
TPS51125

CPU & GFX Power
ISL95831

dGPU Power
TPS51621

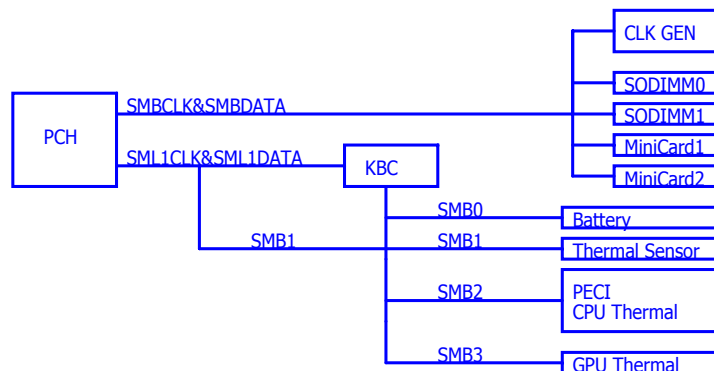
Chipset Power
TPS51117

DDR3 Power
TPS51116

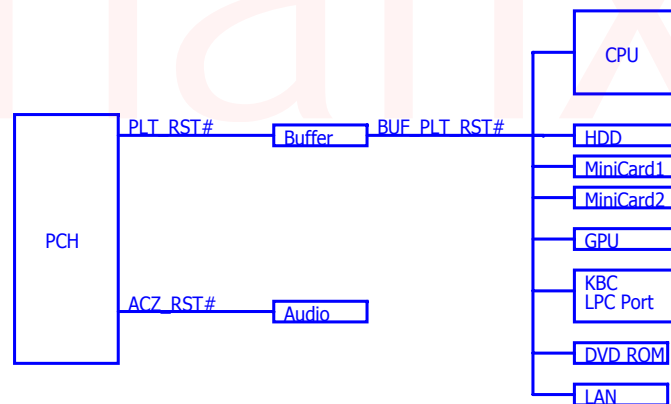
Charger
BQ24725

S3/S4 Control
and Discharge

SMBUS TOPOLOGY



RESET TOPOLOGY



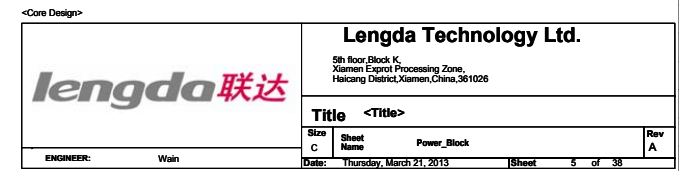
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Size C	Sheet Name	SMBUS & RESET TOPOLOGY	Rev A
ENGINEER:	Wain	Date: Thursday, March 21, 2013	Sheet 3 of 38



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lengda 联达		Title <Title>				
ENGINEER: Wain		Size C	<table><tr><td>Sheet Name</td><td>SMBUS & RESET TOPOLOGY</td><td>Rev A</td></tr></table>	Sheet Name	SMBUS & RESET TOPOLOGY	Rev A
Sheet Name	SMBUS & RESET TOPOLOGY	Rev A				
		Date: Thursday, March 21, 2013	Sheet 4 of 38			

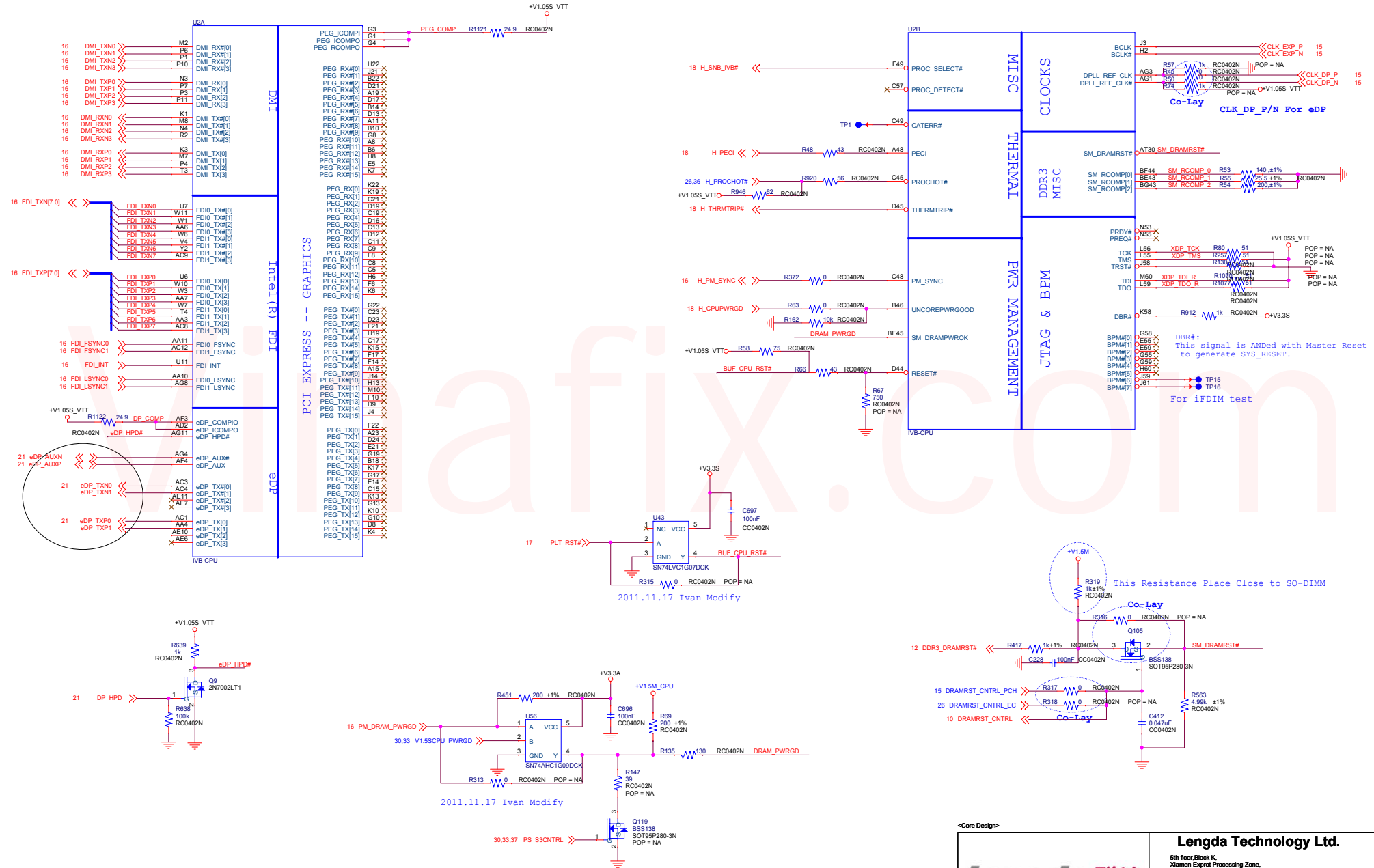
POWER Delivery Architectural Block Diagram



CAD NOTE: PEG ICOMPI and RCOMPO signals should be shorted and routed with
 - max length = 500 mils
 - typical impedance = 43 mohms
 PEG ICOMPO signals should be routed with
 - max length = 500 mils
 - typical impedance = 14.5 mohms

Host Clock Routing Topology

Host clock (100 MHz DMI/BCLK and 120 MHz e-DP clocks) routes out of PCH do not need any series termination.



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Size C Sheet Name CPU1

ENGINEER: Ivan

Date: Thursday, March 21, 2013

Sheet 6 of 38

Rev A

12 M_A_DQ[63..0] << >>

M_A_DQ0 AG6 SA_DQ[0]
M_A_DQ1 AJ6 SA_DQ[1]
M_A_DQ2 AP11 SA_DQ[2]
M_A_DQ3 AL6 SA_DQ[3]
M_A_DQ4 AJ10 SA_DQ[4]
M_A_DQ5 AL8 SA_DQ[5]
M_A_DQ6 AL8 SA_DQ[6]
M_A_DQ7 AL7 SA_DQ[7]
M_A_DQ8 AR11 SA_DQ[8]
M_A_DQ9 AP6 SA_DQ[9]
M_A_DQ10 AU6 SA_DQ[10]
M_A_DQ11 AV9 SA_DQ[11]
M_A_DQ12 AR6 SA_DQ[12]
M_A_DQ13 AP8 SA_DQ[13]
M_A_DQ14 AT13 SA_DQ[14]
M_A_DQ15 AU13 SA_DQ[15]
M_A_DQ16 BC7 SA_DQ[16]
M_A_DQ17 BB7 SA_DQ[17]
M_A_DQ18 BA13 SA_DQ[18]
M_A_DQ19 BB11 SA_DQ[19]
M_A_DQ20 BA7 SA_DQ[20]
M_A_DQ21 BA9 SA_DQ[21]
M_A_DQ22 BB9 SA_DQ[22]
M_A_DQ23 AY13 SA_DQ[23]
M_A_DQ24 AV14 SA_DQ[24]
M_A_DQ25 AR14 SA_DQ[25]
M_A_DQ26 AY17 SA_DQ[26]
M_A_DQ27 AR19 SA_DQ[27]
M_A_DQ28 BA14 SA_DQ[28]
M_A_DQ29 AU14 SA_DQ[29]
M_A_DQ30 BB14 SA_DQ[30]
M_A_DQ31 BB17 SA_DQ[31]
M_A_DQ32 BA45 SA_DQ[32]
M_A_DQ33 AR43 SA_DQ[33]
M_A_DQ34 AW48 SA_DQ[34]
M_A_DQ35 BC48 SA_DQ[35]
M_A_DQ36 BC45 SA_DQ[36]
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M_A_DQ38 AT48 SA_DQ[38]
M_A_DQ39 AY48 SA_DQ[39]
M_A_DQ40 BA49 SA_DQ[40]
M_A_DQ41 AV49 SA_DQ[41]
M_A_DQ42 BB51 SA_DQ[42]
M_A_DQ43 AY53 SA_DQ[43]
M_A_DQ44 BB49 SA_DQ[44]
M_A_DQ45 AU49 SA_DQ[45]
M_A_DQ46 BA53 SA_DQ[46]
M_A_DQ47 BB55 SA_DQ[47]
M_A_DQ48 BA55 SA_DQ[48]
M_A_DQ49 AV56 SA_DQ[49]
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M_A_DQ52 AV54 SA_DQ[52]
M_A_DQ53 AT54 SA_DQ[53]
M_A_DQ54 AP56 SA_DQ[54]
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M_A_DQ56 AN57 SA_DQ[56]
M_A_DQ57 AN53 SA_DQ[57]
M_A_DQ58 AG56 SA_DQ[58]
M_A_DQ59 AG53 SA_DQ[59]
M_A_DQ60 AN52 SA_DQ[60]
M_A_DQ61 AG56 SA_DQ[61]
M_A_DQ62 AG56 SA_DQ[62]
M_A_DQ63 AK56 SA_DQ[63]

DDR SYSTEM MEMORY A

SA_CLK[0] AU36 >>> M_CLK_DDR0 12
SA_CLK[1] AU36 >>> M_CLK_DDR#0 12
SA_CKE[0] AY26 >>> M_CKE0 12

SA_CLK[1] AT40 >>> M_CLK_DDR1 12
SA_CLK[1] AU40 >>> M_CLK_DDR#1 12
SA_CKE[1] BB26 >>> M_CKE1 12

SA_CS#[0] BB40 >>> M_CS#0 12
SA_CS#[1] BC41 >>> M_CS#1 12

SA_ODT[0] AY40 >>> M_ODT0 12
SA_ODT[1] BA41 >>> M_ODT1 12

SA_DQS#0 AL11 M_A_DQS#0 <<< >>> M_A_DQS#7..0] 12
SA_DQS#1 AR8 M_A_DQS#1
SA_DQS#2 AV11 M_A_DQS#2
SA_DQS#3 AT17 M_A_DQS#3
SA_DQS#4 AV45 M_A_DQS#4
SA_DQS#5 AY51 M_A_DQS#5
SA_DQS#6 AT55 M_A_DQS#6
SA_DQS#7 AK55 M_A_DQS#7

SA_DQS[0] AJ11 M_A_DQS0 <<< >>> M_A_DQS#7..0] 12
SA_DQS[1] AR10 M_A_DQS1
SA_DQS[2] AY11 M_A_DQS2
SA_DQS[3] AU17 M_A_DQS3
SA_DQS[4] AW45 M_A_DQS4
SA_DQS[5] AV51 M_A_DQS5
SA_DQS[6] AT55 M_A_DQS6
SA_DQS[7] AK54 M_A_DQS7

SA_MA[0] BG35 M_A_A0 <<< >>> M_A_A[15..0] 12
SA_MA[1] BB34 M_A_A1
SA_MA[2] BE35 M_A_A2
SA_MA[3] BD35 M_A_A3
SA_MA[4] AT34 M_A_A4
SA_MA[5] AU34 M_A_A5
SA_MA[6] BB32 M_A_A6
SA_MA[7] AT32 M_A_A7
SA_MA[8] AY32 M_A_A8
SA_MA[9] AV32 M_A_A9
SA_MA[10] BE37 M_A_A10
SA_MA[11] BA30 M_A_A11
SA_MA[12] BC30 M_A_A12
SA_MA[13] AW41 M_A_A13
SA_MA[14] AY28 M_A_A14
SA_MA[15] AU26 M_A_A15

12 M_A_BS0 <<< BD37 SA_BS[0]
12 M_A_BS1 <<< BF36 SA_BS[1]
12 M_A_BS2 <<< BA28 SA_BS[2]

12 M_A_CAS# <<< BE39 SA_CAS#
12 M_A_RAS# <<< BD30 SA_RAS#
12 M_A_WE# <<< AT41 SA_WE#

VB-CPU

U20

AL4 SB_DQ[0]
XAL11 SB_DQ[1]
XAR3 SB_DQ[2]
XAR4 SB_DQ[3]
XAK4 SB_DQ[4]
XAK3 SB_DQ[5]
XAN4 SB_DQ[6]
XAK1 SB_DQ[7]
XAU4 SB_DQ[8]
XAT2 SB_DQ[9]
XAU4 SB_DQ[10]
XAU3 SB_DQ[11]
XAK3 SB_DQ[12]
XAY2 SB_DQ[13]
XBA3 SB_DQ[14]
XBC9 SB_DQ[15]
XBD9 SB_DQ[16]
XBD13 SB_DQ[17]
XBD10 SB_DQ[18]
XBF8 SB_DQ[19]
XBD14 SB_DQ[20]
XBD13 SB_DQ[21]
XBF16 SB_DQ[22]
XBE17 SB_DQ[23]
XBE18 SB_DQ[24]
XBE17 SB_DQ[25]
XBE17 SB_DQ[26]
XBE14 SB_DQ[27]
XBE14 SB_DQ[28]
XBE18 SB_DQ[29]
XBF19 SB_DQ[30]
XBD50 SB_DQ[31]
XBF48 SB_DQ[32]
XBD33 SB_DQ[33]
XBF32 SB_DQ[34]
XBD49 SB_DQ[35]
XBD49 SB_DQ[36]
XBD54 SB_DQ[37]
XBE53 SB_DQ[38]
XBF66 SB_DQ[39]
XBE57 SB_DQ[40]
XBC59 SB_DQ[41]
XAY60 SB_DQ[42]
XBE54 SB_DQ[43]
XBG54 SB_DQ[44]
XBA58 SB_DQ[45]
XAW59 SB_DQ[46]
XAW58 SB_DQ[47]
XAU58 SB_DQ[48]
XAN51 SB_DQ[49]
XAN59 SB_DQ[50]
XAU59 SB_DQ[51]
XAU59 SB_DQ[52]
XAU51 SB_DQ[53]
XAN58 SB_DQ[54]
XAR58 SB_DQ[55]
XAK58 SB_DQ[56]
XAL58 SB_DQ[57]
XAG58 SB_DQ[58]
XAG59 SB_DQ[59]
XAM60 SB_DQ[60]
XAL59 SB_DQ[61]
XAF61 SB_DQ[62]
XAH60 SB_DQ[63]

DDR SYSTEM MEMORY B

SB_CLK[0] BA34 >>> M_CLK_DDR0 12
SB_CLK[0] AV34 >>> M_CLK_DDR#0 12
SB_CKE[0] AR22 >>> M_CKE0 12

SB_CLK[1] BA36 >>> M_CLK_DDR1 12
SB_CLK[1] BF27 >>> M_CLK_DDR#1 12
SB_CKE[1] BE47 >>> M_CKE1 12

SB_CS#0 BA41 >>> M_CS#0 12
SB_CS#1 BE47 >>> M_CS#1 12

SB_ODT[0] AT43 >>> M_ODT0 12
SB_ODT[1] BG47 >>> M_ODT1 12

SB_DQS#0 AL3 <<< >>> M_A_DQS#7..0] 12
SB_DQS#1 AV3 <<< >>> M_A_DQS#7..0] 12
SB_DQS#2 BT17 <<< >>> M_A_DQS#7..0] 12
SB_DQS#3 BD17 <<< >>> M_A_DQS#7..0] 12
SB_DQS#4 BG57 <<< >>> M_A_DQS#7..0] 12
SB_DQS#5 BA58 <<< >>> M_A_DQS#7..0] 12
SB_DQS#6 AT60 <<< >>> M_A_DQS#7..0] 12
SB_DQS#7 AK58 <<< >>> M_A_DQS#7..0] 12

SB_DQS[0] AM2 <<< >>> M_A_DQS#7..0] 12
SB_DQS[1] AV17 <<< >>> M_A_DQS#7..0] 12
SB_DQS[2] BE17 <<< >>> M_A_DQS#7..0] 12
SB_DQS[3] BD15 <<< >>> M_A_DQS#7..0] 12
SB_DQS[4] BE17 <<< >>> M_A_DQS#7..0] 12
SB_DQS[5] BA67 <<< >>> M_A_DQS#7..0] 12
SB_DQS[6] AR58 <<< >>> M_A_DQS#7..0] 12
SB_DQS[7] AK67 <<< >>> M_A_DQS#7..0] 12

SB_MA[0] BF32 <<< >>> M_A_A[15..0] 12
SB_MA[1] BE33 <<< >>> M_A_A[15..0] 12
SB_MA[2] BD33 <<< >>> M_A_A[15..0] 12
SB_MA[3] AU34 <<< >>> M_A_A[15..0] 12
SB_MA[4] BD38 <<< >>> M_A_A[15..0] 12
SB_MA[5] AV30 <<< >>> M_A_A[15..0] 12
SB_MA[6] BC30 <<< >>> M_A_A[15..0] 12
SB_MA[7] BD28 <<< >>> M_A_A[15..0] 12
SB_MA[8] BE30 <<< >>> M_A_A[15..0] 12
SB_MA[9] BE28 <<< >>> M_A_A[15..0] 12
SB_MA[10] BD43 <<< >>> M_A_A[15..0] 12
SB_MA[11] AT28 <<< >>> M_A_A[15..0] 12
SB_MA[12] BD45 <<< >>> M_A_A[15..0] 12
SB_MA[13] AT28 <<< >>> M_A_A[15..0] 12
SB_MA[14] AL28 <<< >>> M_A_A[15..0] 12
SB_MA[15] <<< >>> M_A_A[15..0] 12

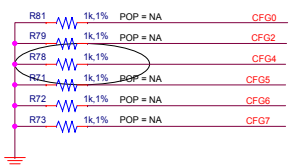
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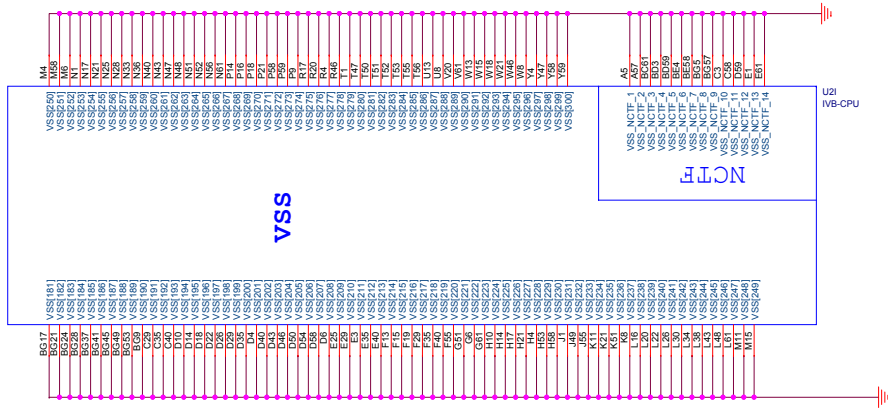
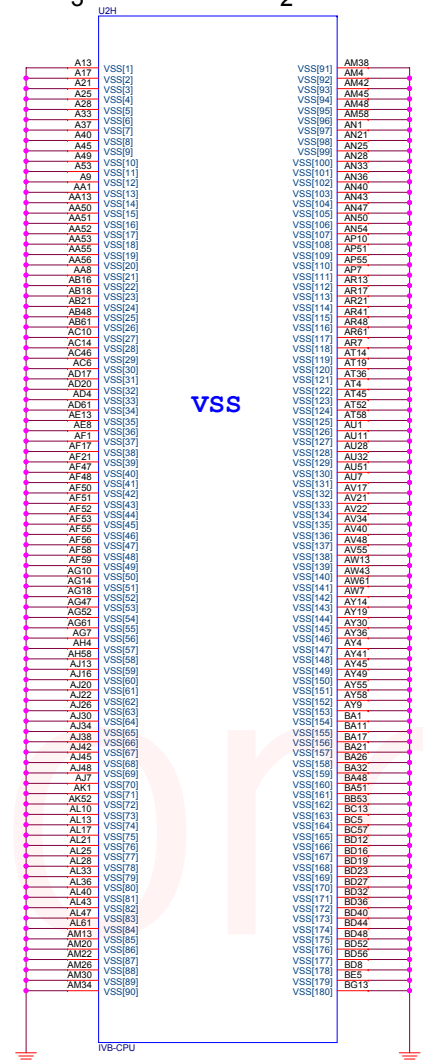
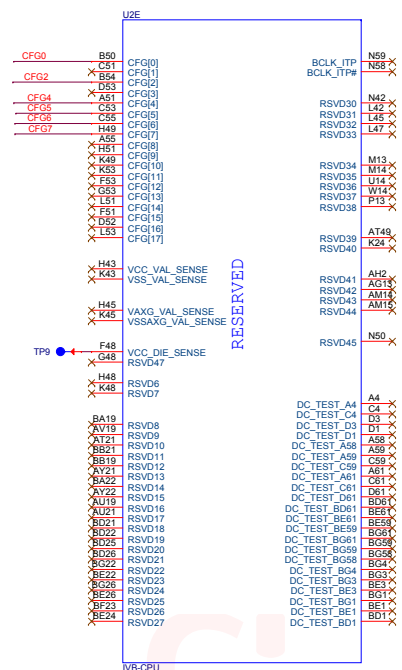
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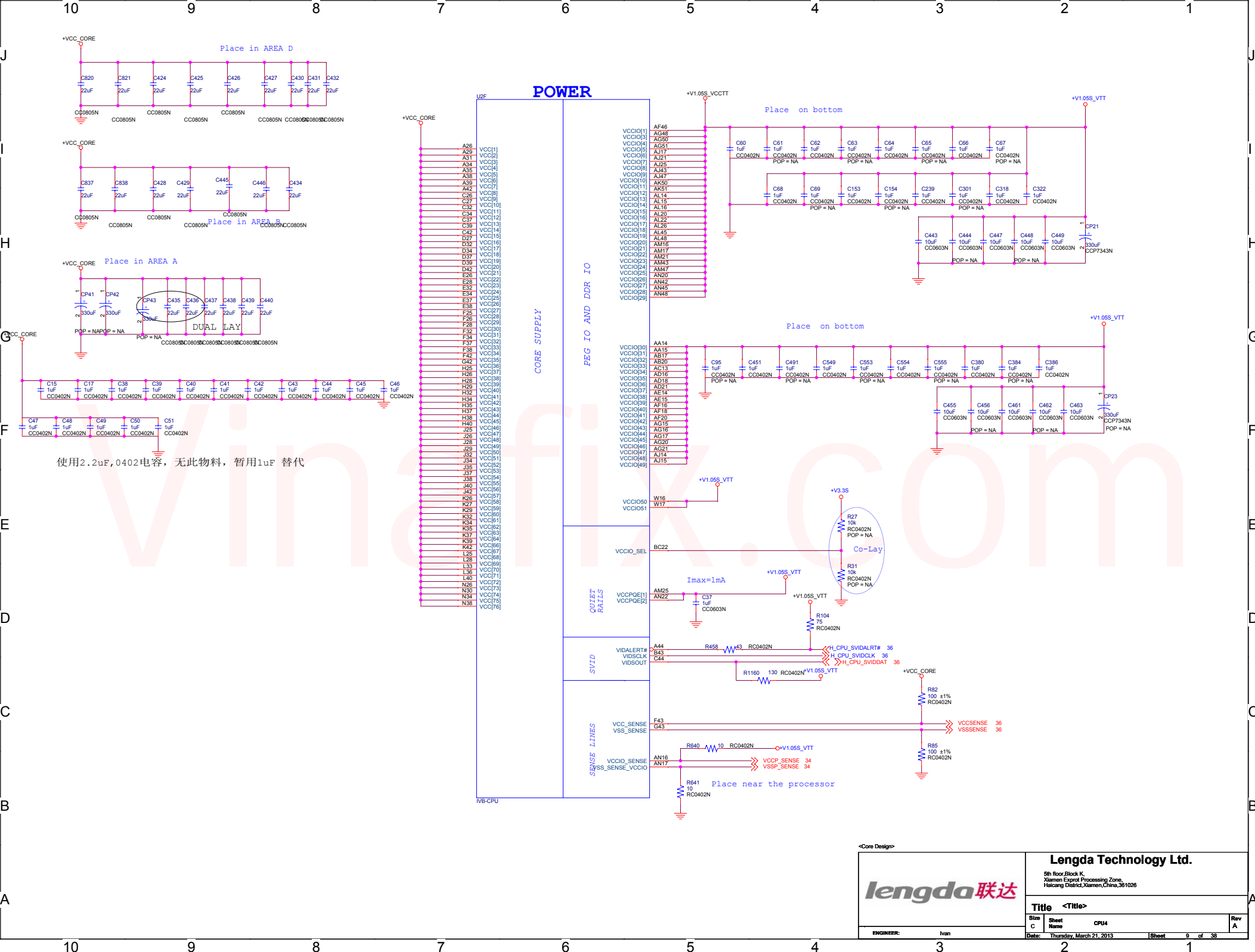
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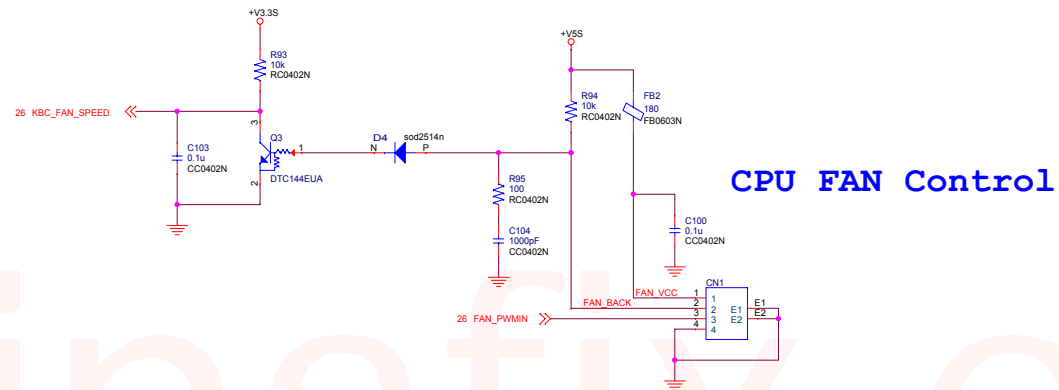
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Size C	Sheet Name CPU2	
ENGINEER: hvan	Date: Thursday, March 21, 2013	Sheet 7 of 38



Processor strap CFG[4] should be pulled low to enable Embedded DisplayPort

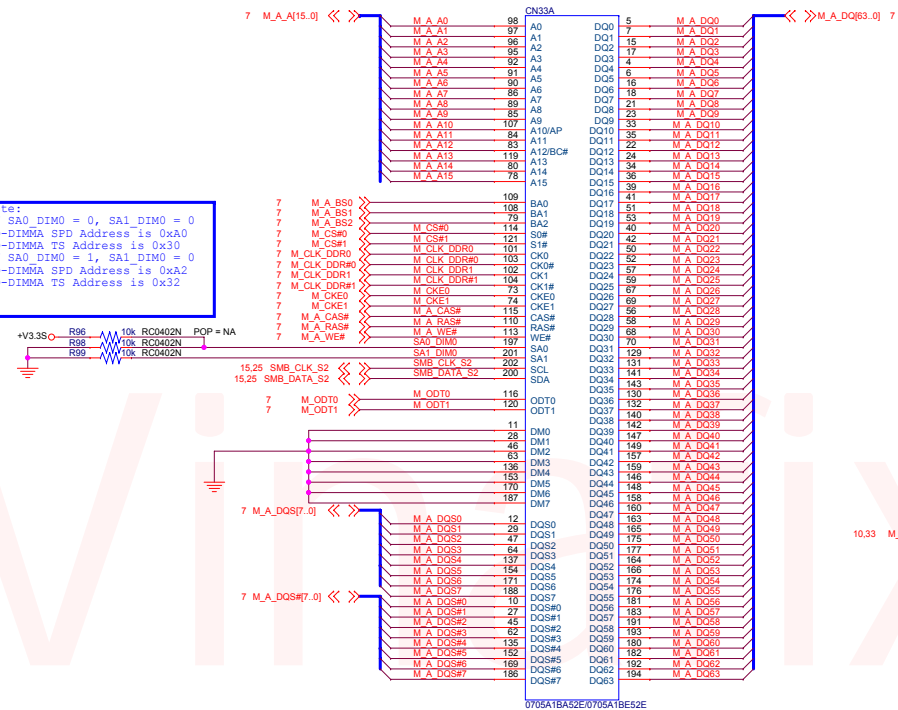




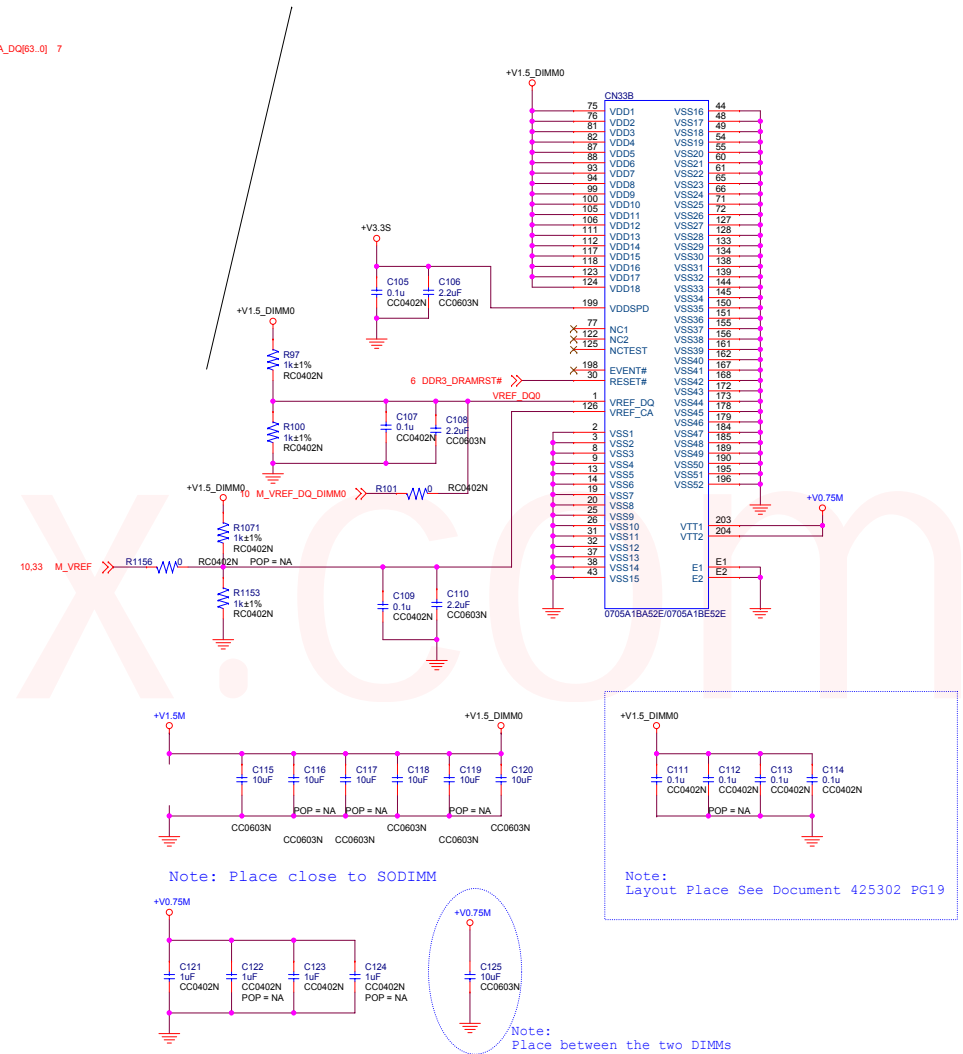


DDR3 SODIMM0

Note:
If SA0_DIM0 = 0, SA1_DIM0 = 0
SO-DIMMA SPD Address is 0xA0
SO-DIMMA TS Address is 0x30
If SA0_DIM0 = 1, SA1_DIM0 = 0
SO-DIMMA SPD Address is 0xA2
SO-DIMMA TS Address is 0x32



Layout Note:
Place the 0-Ω resistors close to SO-DIMM connector.
The overall routing length for both DIMM_VREF traces should be <= 5000 mils (127 mm).
Avoid changing reference plane during the entire routing length. If reference plane has to be changed during the transition to 0-Ω resistors, then GND stitching vias are needed next to resistor pads.
Place GND stitching vias within 100 mils (2.54 mm) of DIMM_VREF traces close to SO-DIMM connector.



Note: Place close to SODIMM

Note: Layout Place See Document 425302 PG19

Note: Place between the two DIMMs

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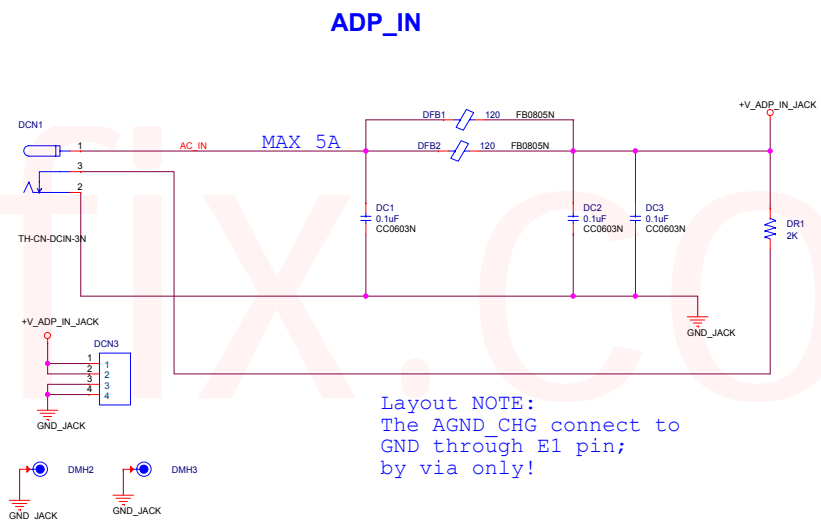
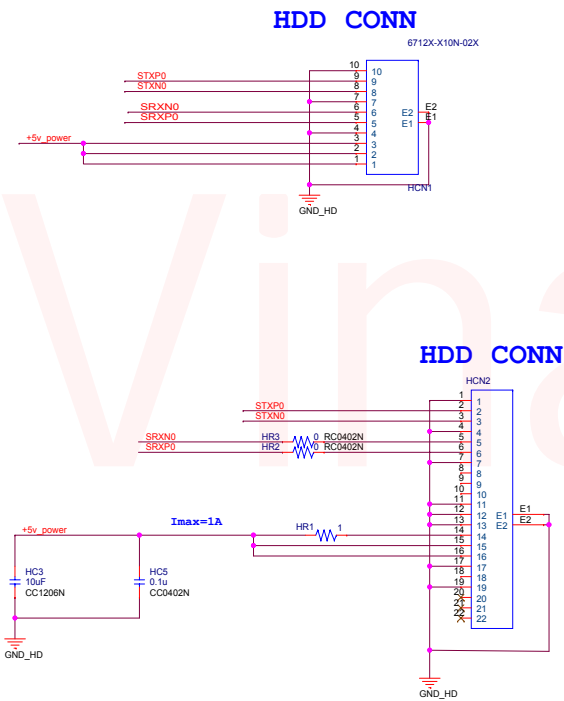
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Title <Title>

Size C Sheet Name DDR3_SODIMM0

ENGINEER: Ivan Date: Thursday, March 21, 2013 Sheet 12 of 38

Rev A



<Core Design>

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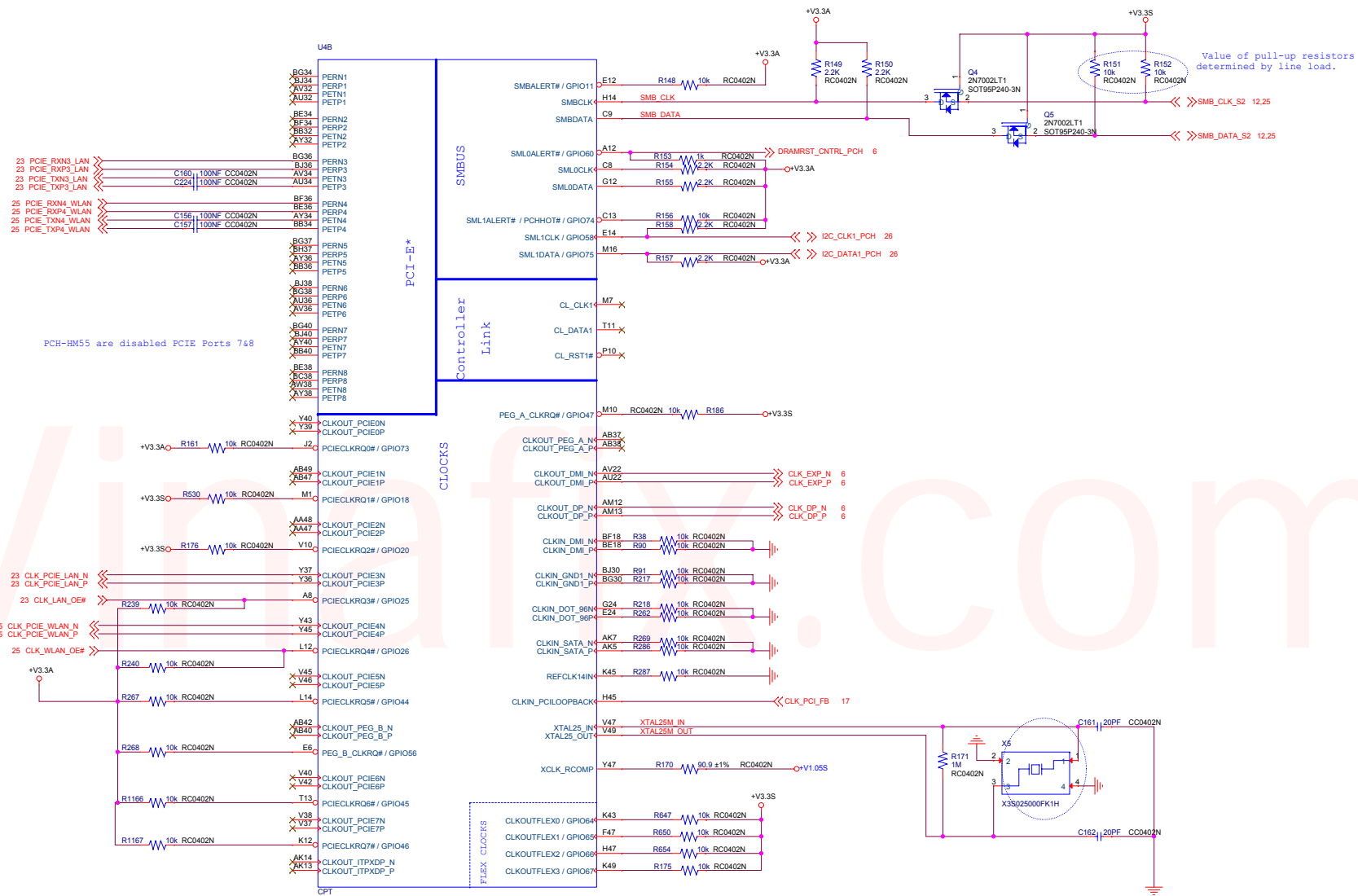
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Date: Thursday, March 21, 2013


ENGINEER: Ivan

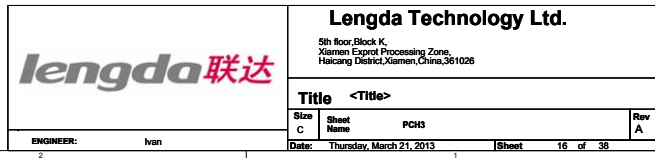
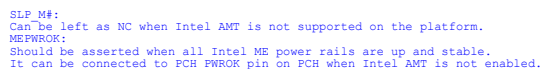
Rev A

Sheet 13 of 38



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Size C	Sheet Name	PCB2	Rev A
ENGINEER: Ivan	Date: Thursday, March 21, 2013	Sheet 15	of 38



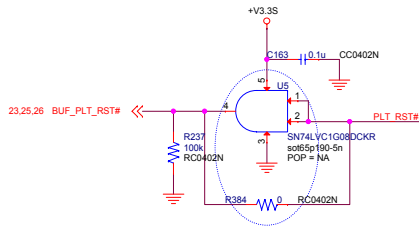
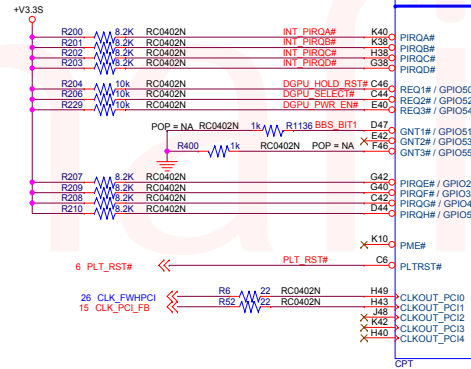
USB 3.0/2.0 Port Pairing

USB 3.0 Port	USB 2.0 Port
Port 1	Port 0
Port 2	Port 1
Port 3	Port 2
Port 4	Port 3

PCH-HM70 disabled USB3.0 Port 3 & 4

Boot BIOS Strap		
PCI_GNT#1	PCI_GNT#0	Boot BIOS Location
0	1	TPC
1	0	Reserved (NAND)
1	1	PCI
1	1	SPI

A16 swap override Strap/Top-Block Swap Override jumper	
PCI_GNT#3	Low = A16 swap override/Top-Block Swap Override enabled High = Default



Allocation	USB Devices
USB0	USB3.0 Port1
USB1	Fingerprint
USB2	Port 2
USB3	Cardreader
USB4	NA
USB5	NA
USB8	Port 3
USB9	Camera
USB10	WLAN
USB11	TOUCH PANEL
USB12	NA
USB13	NA

PCH-HM70 disabled USB2.0 Port 4,5,6,7 & 12,13
PCH-HM76 disabled USB2.0 Port 6,7

OC Pin.	PCH Mapping
OC#0.	Port 0 & 1.
OC#1.	Port 2 & 3.
OC#2.	Port 4 & 5.
OC#3.	Port 6 & 7.
OC#4.	Port 8 & 9.
OC#5.	Port 10 & 11.
OC#6.	Port 12 & 13.
OC#7.	Floater OC# (not used).

OC#[3:0] can only be used for EHCI Controller 1
OC#[4:7] can only be used for EHCI Controller 2

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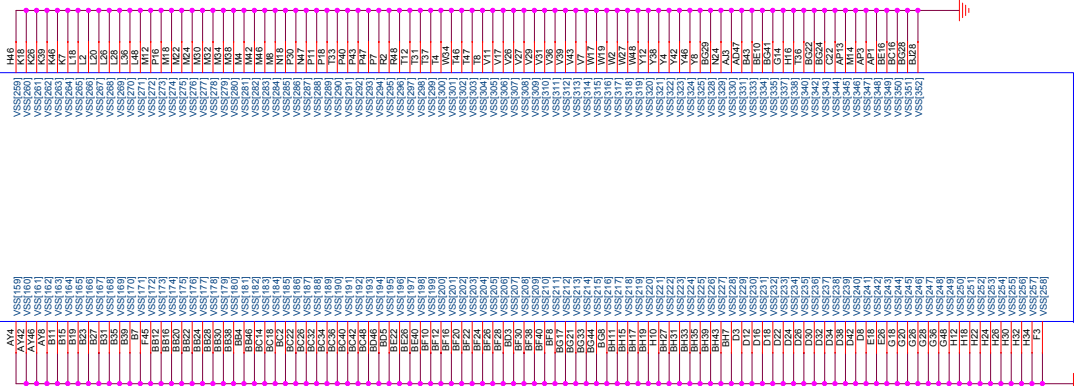
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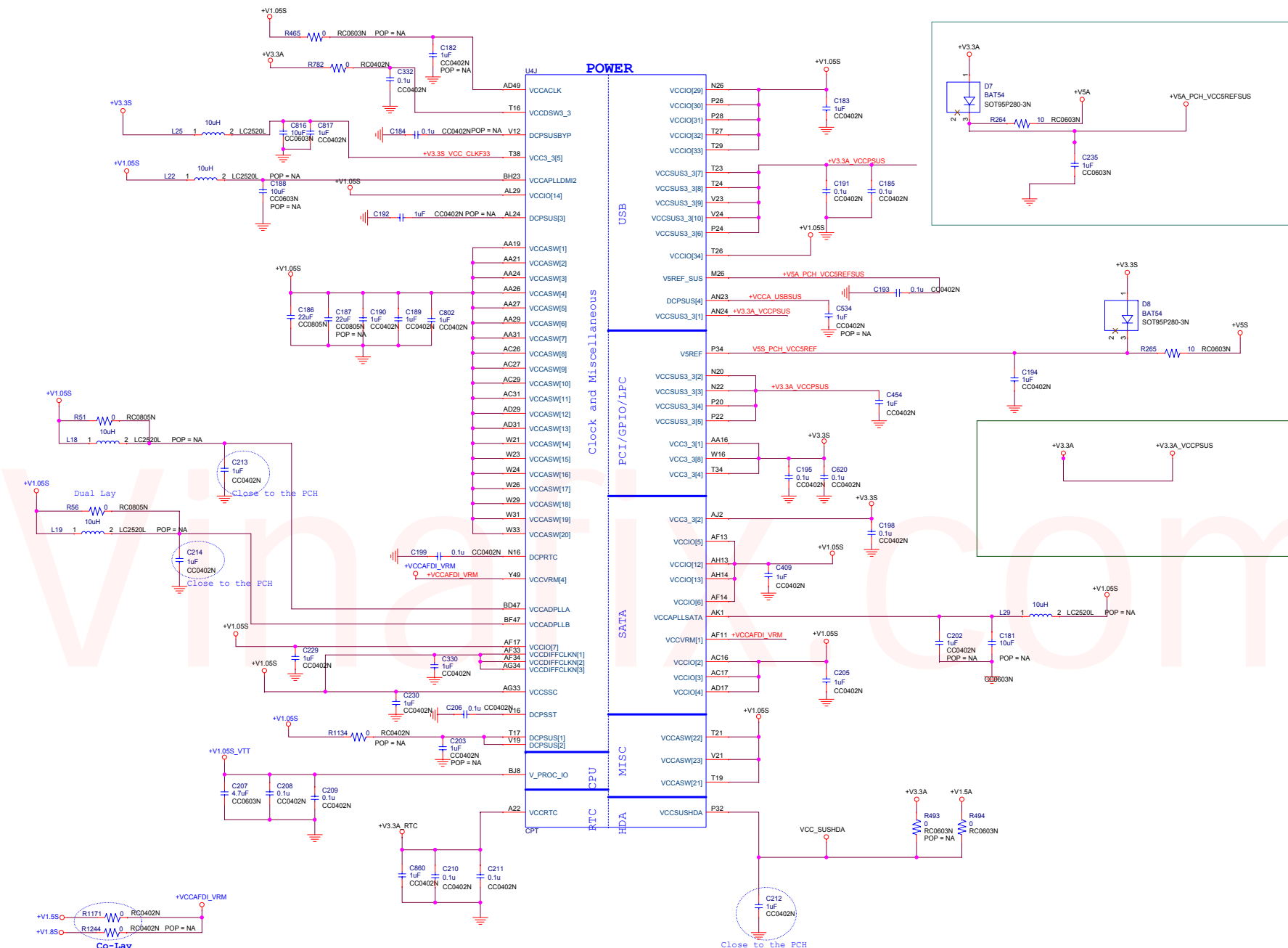
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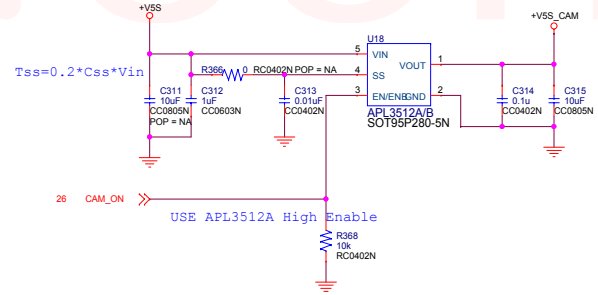
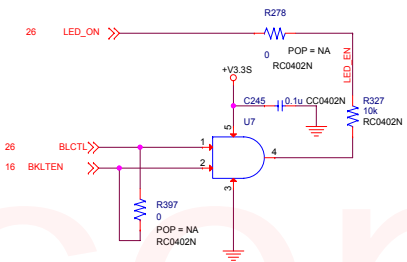
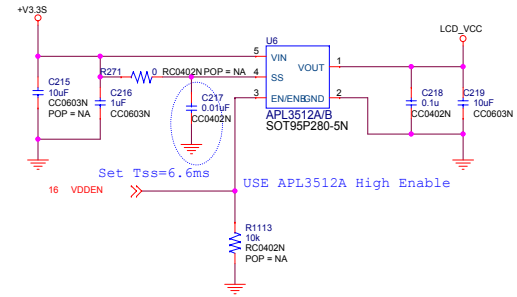
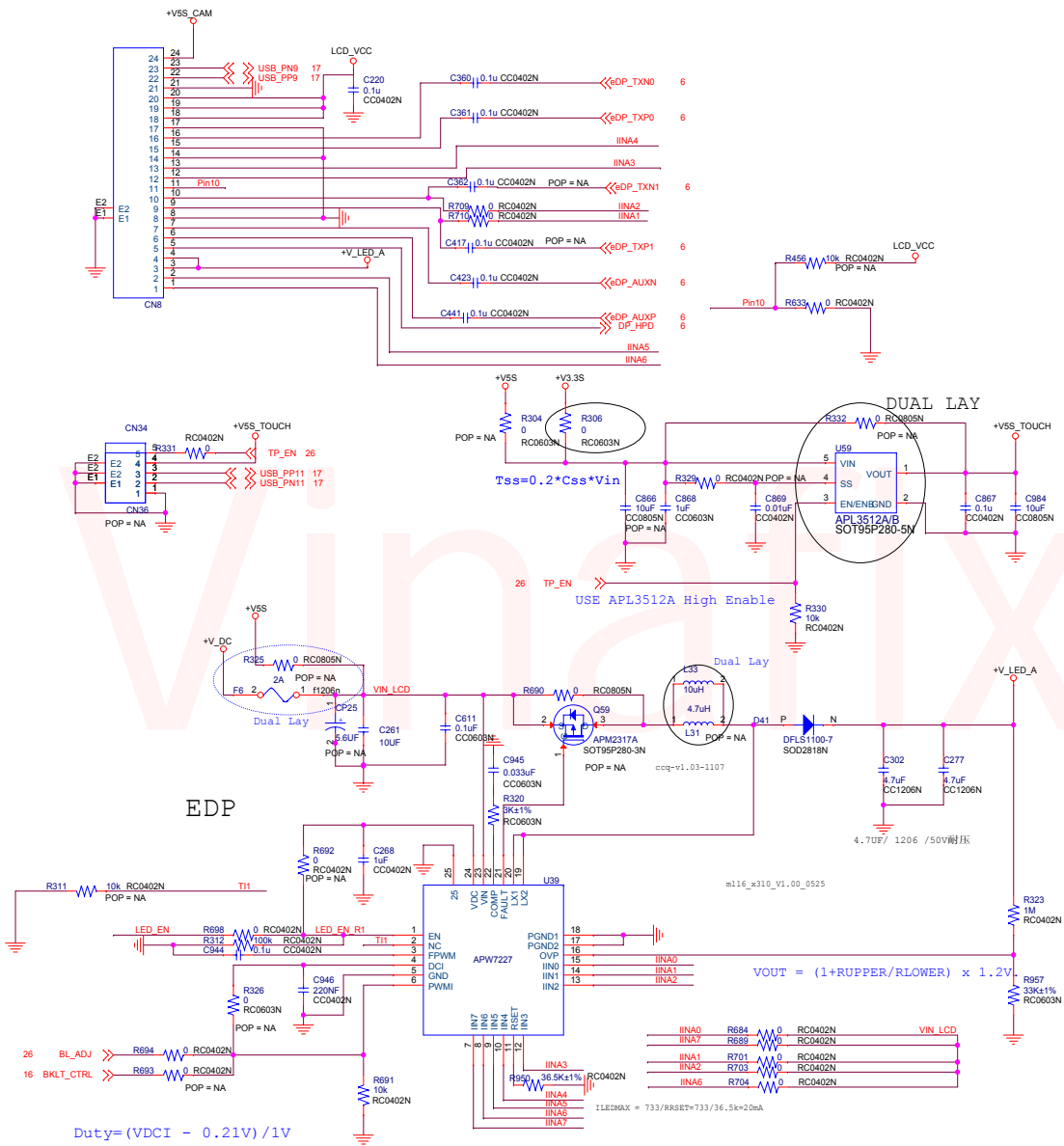
Size C Sheet Name PCH4

ENGINEER: Ivan Date: Thursday, March 21, 2013 Sheet 17 of 38





LVDS Connector



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Title	<Title>
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Size	Sheet	LCD CONN
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C	Name	LCD CONN
1	1	1

Date: Monday, March 25, 2013 Sheet 21 of 38

ENGINEER

Ivan

Date:

Name	
Monde	

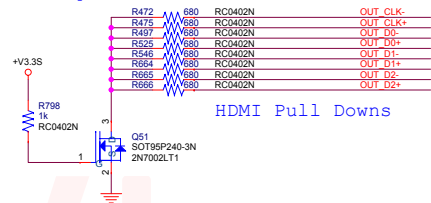
25 2013

Sheet

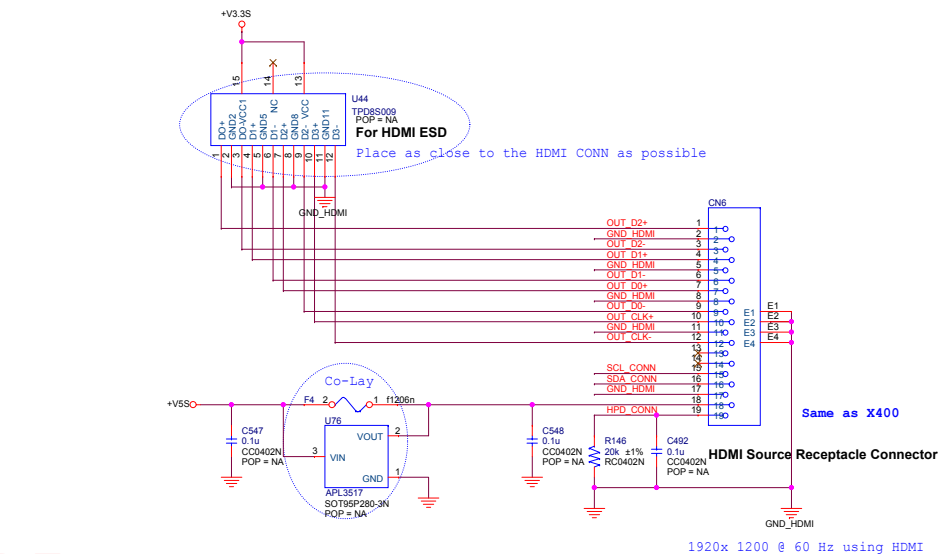
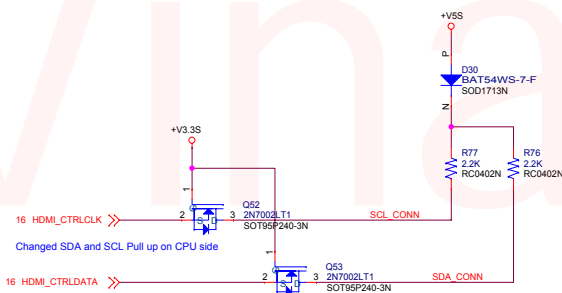
21 of 38

16	TMDS_DATA0+	C545	0.1u	CC0402N	OUT_D2+
16	TMDS_DATA0-	C540	0.1u	CC0402N	OUT_D2-
16	TMDS_DATA1+	C539	0.1u	CC0402N	OUT_D1+
16	TMDS_DATA1-	C542	0.1u	CC0402N	OUT_D1-
16	TMDS_DATA2+	C541	0.1u	CC0402N	OUT_D0+
16	TMDS_DATA2-	C511	0.1u	CC0402N	OUT_D0-
16	TMDS_CLKP	C537	0.1u	CC0402N	OUT_CLK+
16	TMDS_CLKN	C538	0.1u	CC0402N	OUT_CLK-

Layout Note: Place these Resistors close to HDMI CONN



HDMI Pull Downs



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Title <Title>		Rev A	
Size C	Sheet Name	HDMI Port	Rev A
ENGINEER: Ivan	Date: Thursday, March 21, 2013	Sheet 22	of 38

notice: if use ALC269, then r226,r227 is used r226, c243 is NC.
if use ALC269Q, then use R226,C243, r226,r227 is NC

<<Attention>>
Surges of PVDD >7V duration 0.1ms when class D amplifier is working may damage the amplifier, 10uF tantalum capacitors are required at PVDD1 and PVDD2 to suppress the surge.

Place next to pin 39, and Tantalum capacitor is required for C303

Place next to pin 46, and Tantalum capacitor is required for C237

<<Attention>>
For power_on/off de-pop circuit and system booting warning signal: Please System BIOS Engineer Note :
1. If you want the system make warning signal after power on , please let EC_MUTE# High first.
2. When you want to exit your Bios Programming Code, please let the EC_MUTE# Low. (The programming is different from before .)

PD# = 0V : Power down Class D SPK amplifier
PD# = 3.3V : Power up Class D SPK amplifier

Tied at one point only under the ALC269 or near the ALC269

<<Attention>>
If mount the LC filter (L19-L12;C295/C299;C300/C293/C294/C296), Please let them together and close to codec. If the PCB trace and Speaker wire length is less than 20cm, don't need the LC filter (L19-L12;C295/C299) to eliminate the EMI, if L19,L10,L11,L12 are replaced by 0 ohm/1.6A resistor (please don't use general bead, because it may influence the THD+N quality) , and C295,C299 should be NC. And, please make the trace length/ Speaker wire length of SPK L+/L-/R+/R- be the same as possible as you can.
C300/C293/C294/C296 are reserved for EMI fine-tune; For EMI issue, please also refer our ALC269 Layout guide document

For ALC269

For ALC269Q

MIC Jack

Audio Jack

match to R298 R299

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Title <Title>

Sheet Name Audio Codec

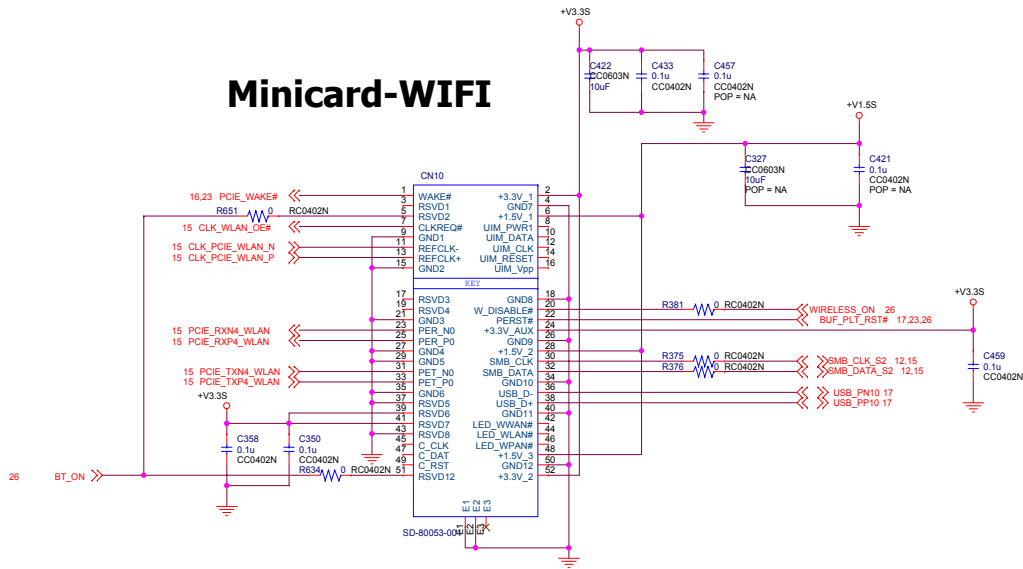
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Sheet 1 of 38

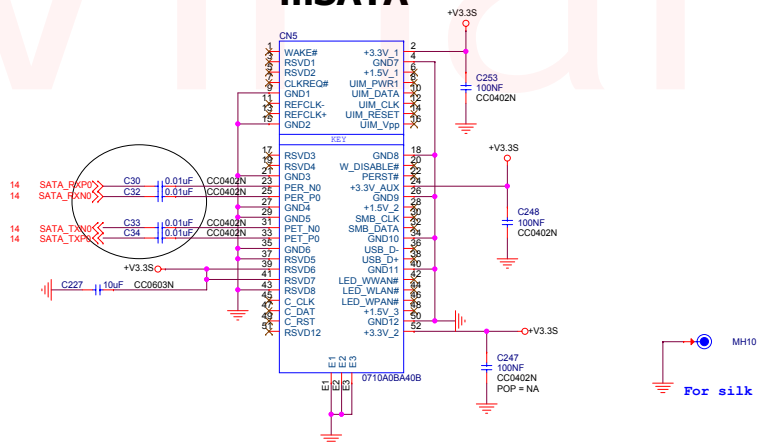
Rev A

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Minicard-WIFI



mSATA



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Title <Title>

Size C **Sheet** Name **Minicard-WIFI & mSATA**

ENGINEER: Ivan

Date: Thursday, March 21, 2013 **Sheet** 25 of 38 **Rev** A

5

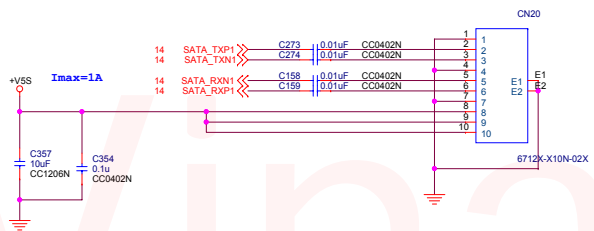
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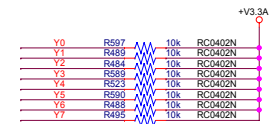
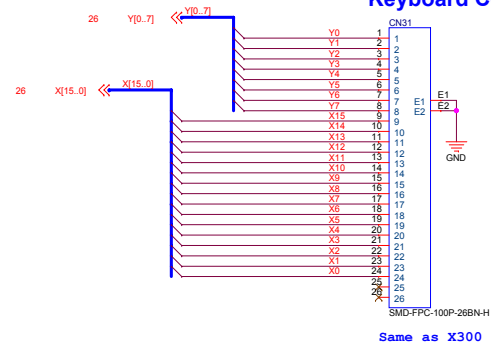
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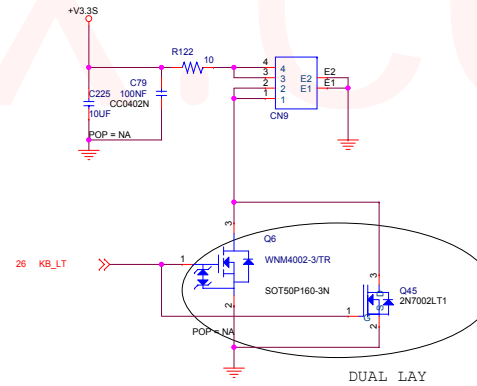
HDD CONN



Keyboard Connector



KB LIGHT CONN



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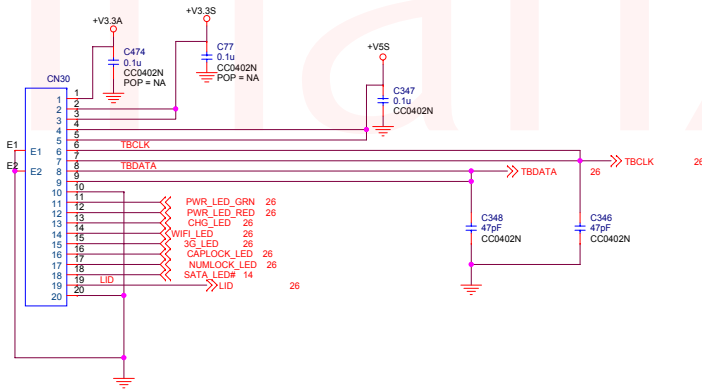
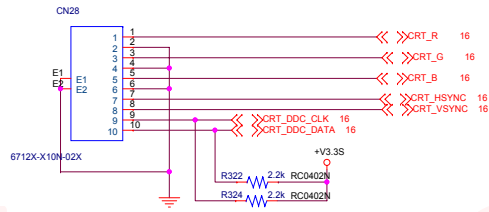
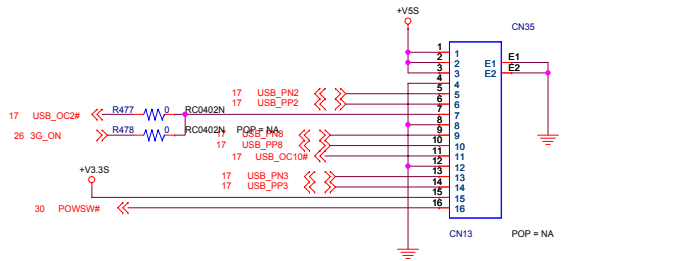
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Size C **Sheet** Name **SATA Port & KB CONN**

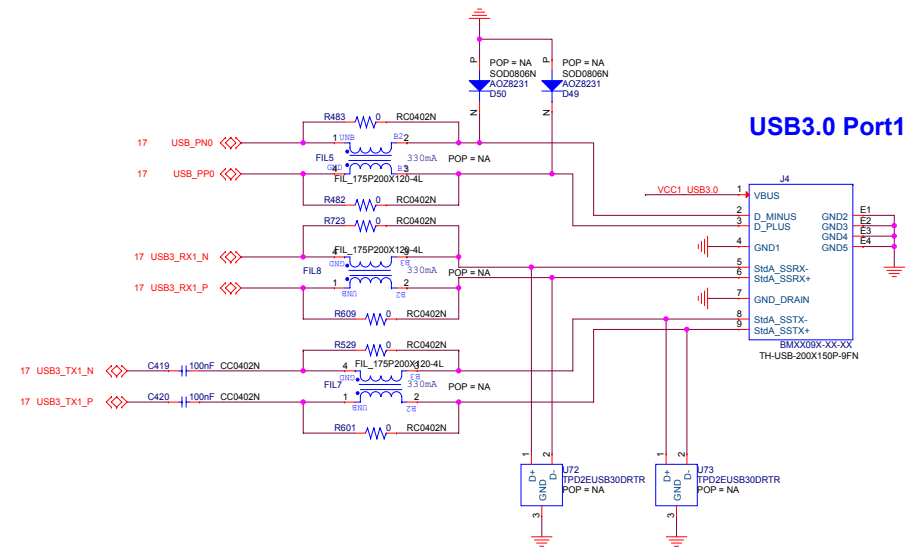
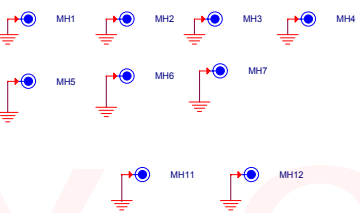
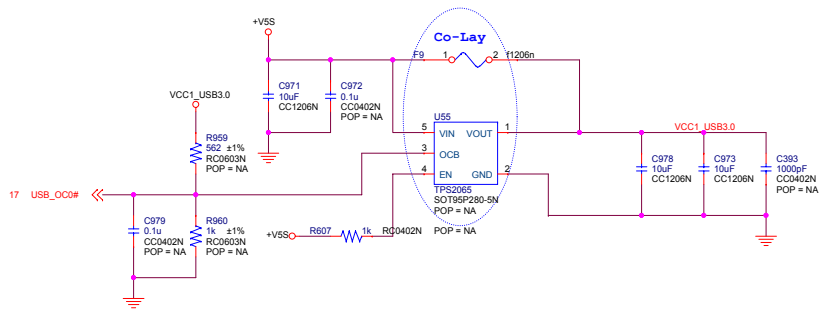
ENGINEER: Ivan **Date:** Monday, March 25, 2013 **Sheet** 27 of 38 **Rev** A

TO USB BOARD

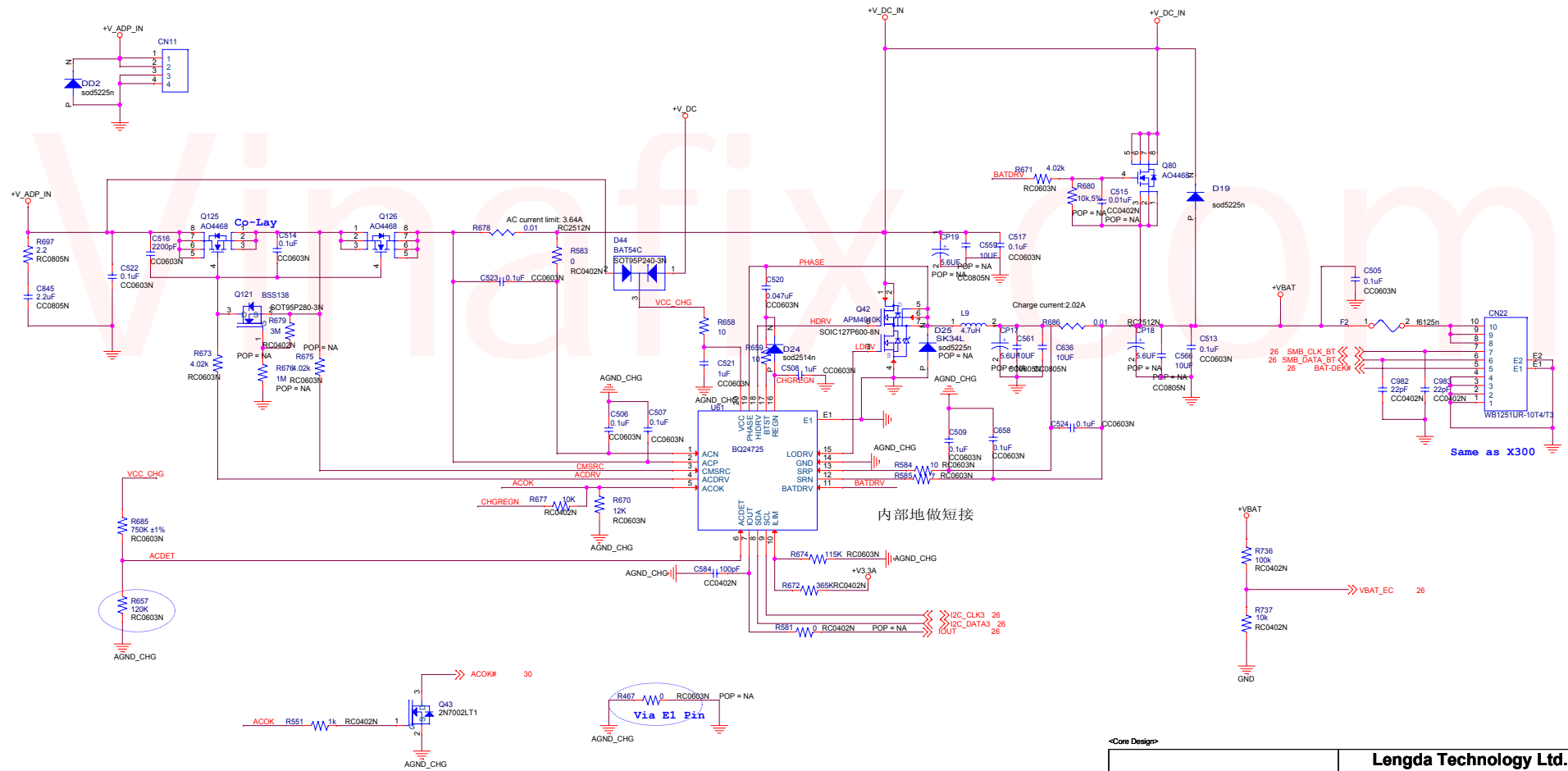


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ENGINEER: Ivan		Size C	Sheet 28 of 38
Date: Thursday, March 21, 2013		Sheet 28 of 38	Rev A

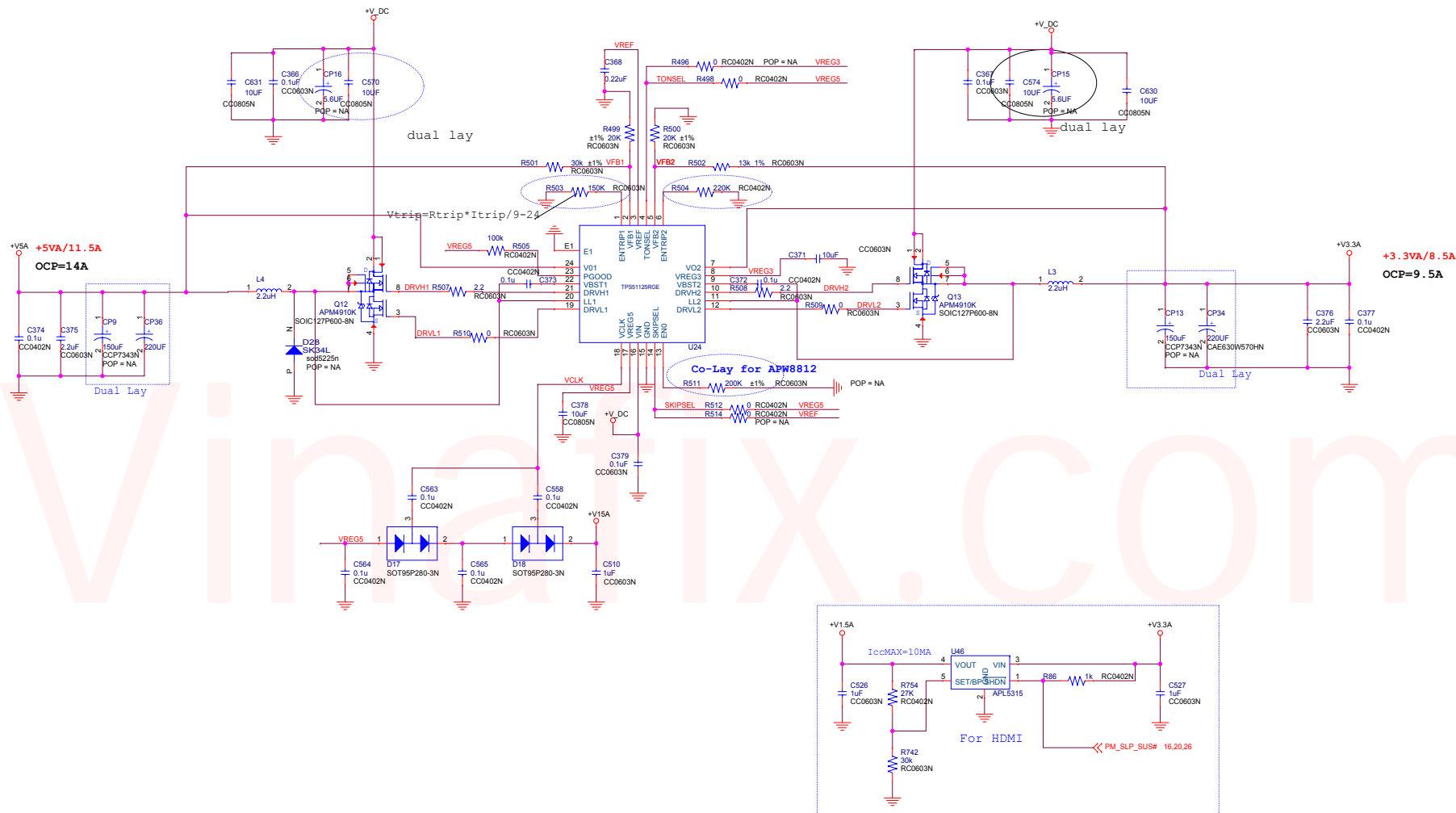


TO DCIN_BOARD




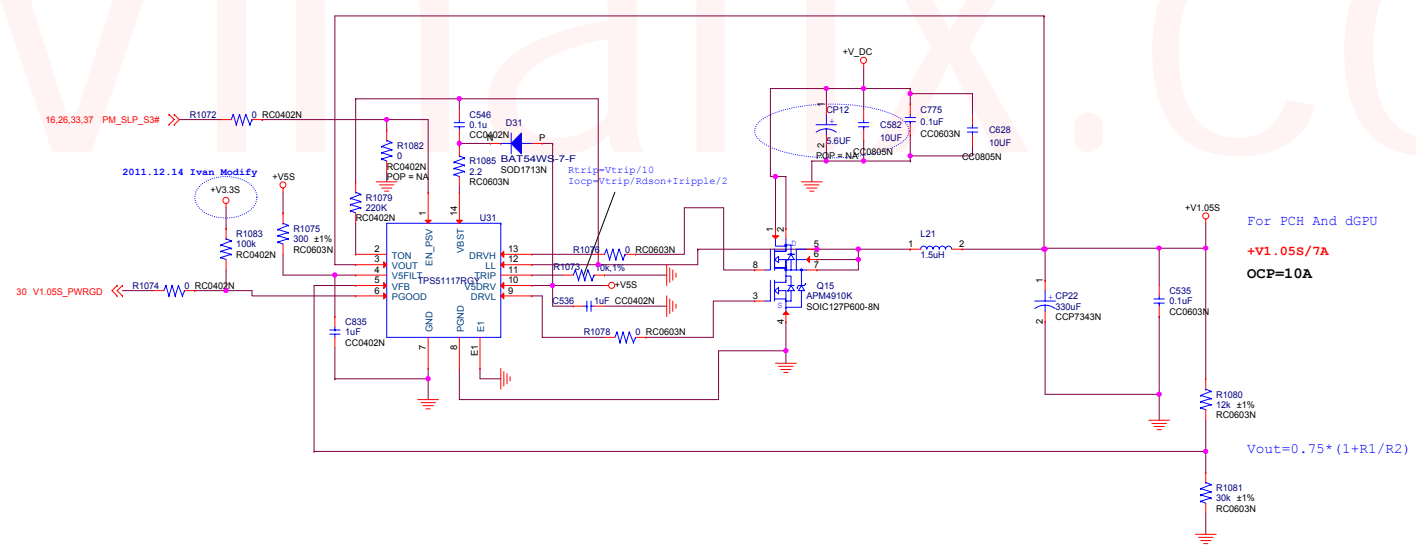
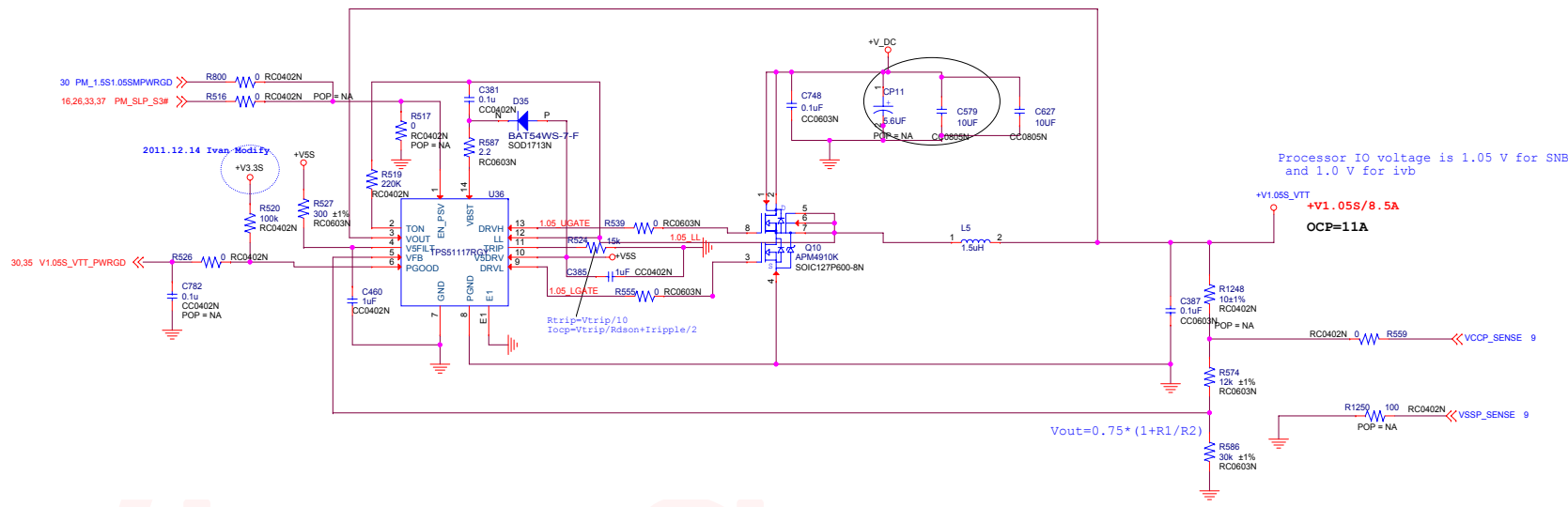
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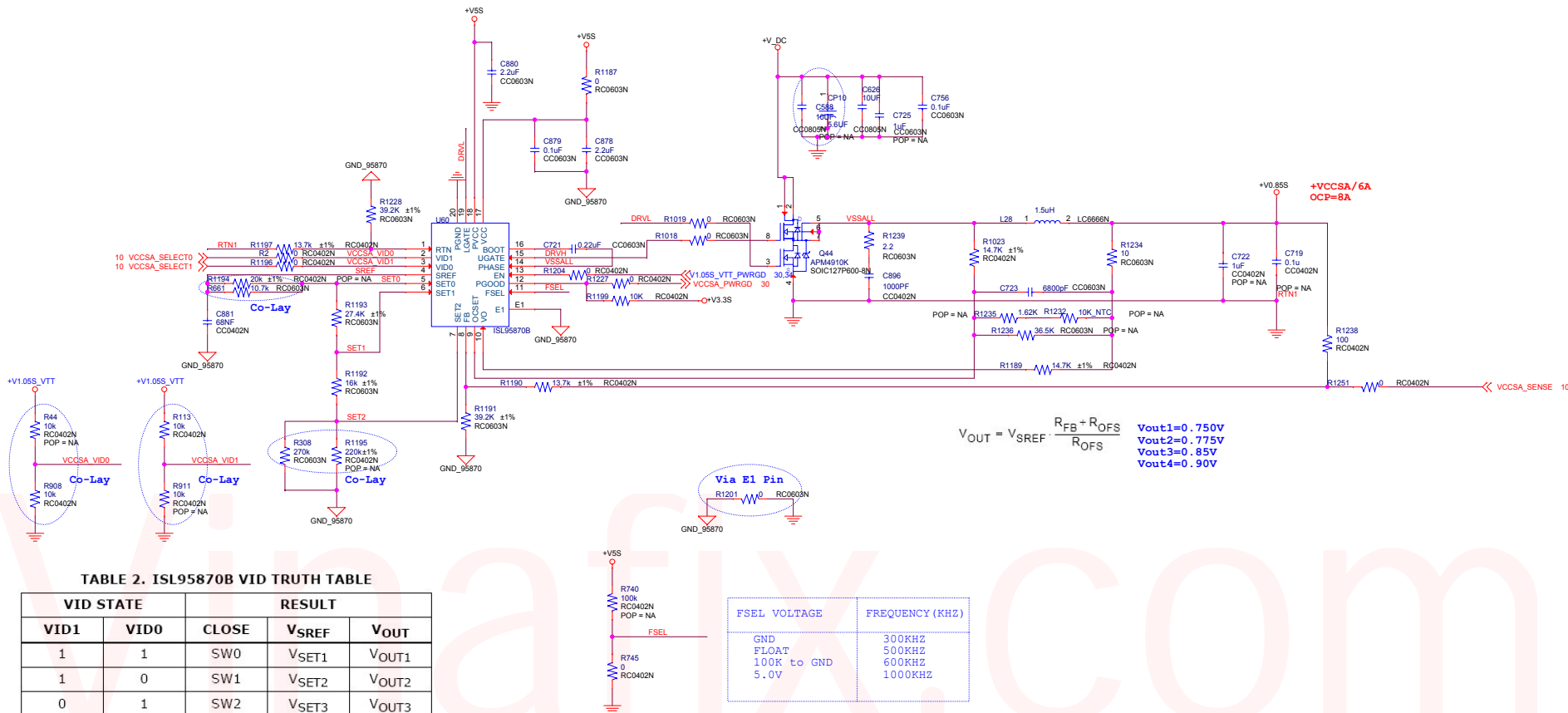
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		Title <Title>	
Size C	Sheet Name	Power Charger & Battery Conn	
ENGINEER: Ivan	Date: Monday, March 25, 2013	Sheet 31 of 38	Rev A



<Core Design>

		Lengda Technology Ltd. 5th floor Block K, Xiamen Export Processing Zone, Haicang District, Xiamen, China, 361026	
		Title <Title> Sheet Name Power_System	
ENGINEER: Ivan	Size C	Sheet 32 of 38	Rev A





The ISL95870B V_{SET1} setpoint is written as Equation 21:

$$V_{SET1} = V_{REF} \quad (\text{EQ. 21})$$

The ISL95870B V_{SET2} setpoint is written as Equation 22:

$$V_{SET2} = V_{REF} \cdot \left(1 + \frac{R_{SET1}}{R_{SET2} + R_{SET3} + R_{SET4}} \right) \quad (\text{EQ. 22})$$


The ISL95870B V_{SET3} setpoint is written as Equation 23:

$$V_{SET3} = V_{REF} \cdot \left(1 + \frac{R_{SET1} + R_{SET2}}{R_{SET3} + R_{SET4}} \right) \quad (\text{EQ. 23})$$

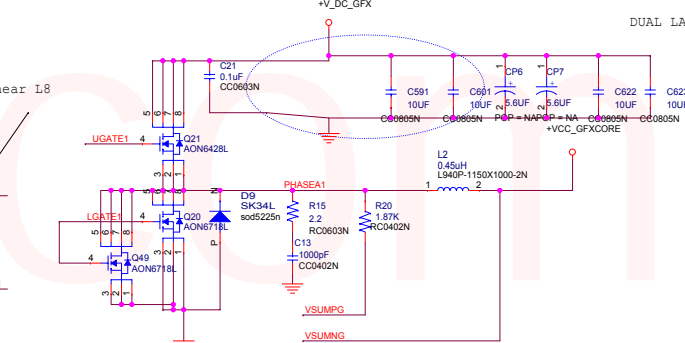
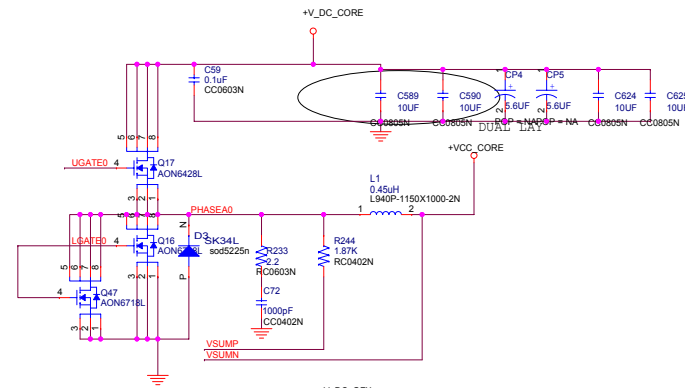
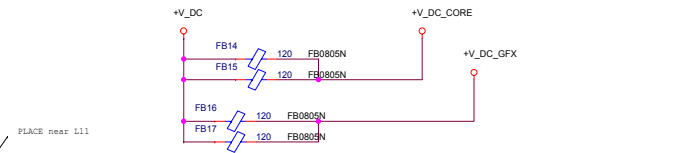
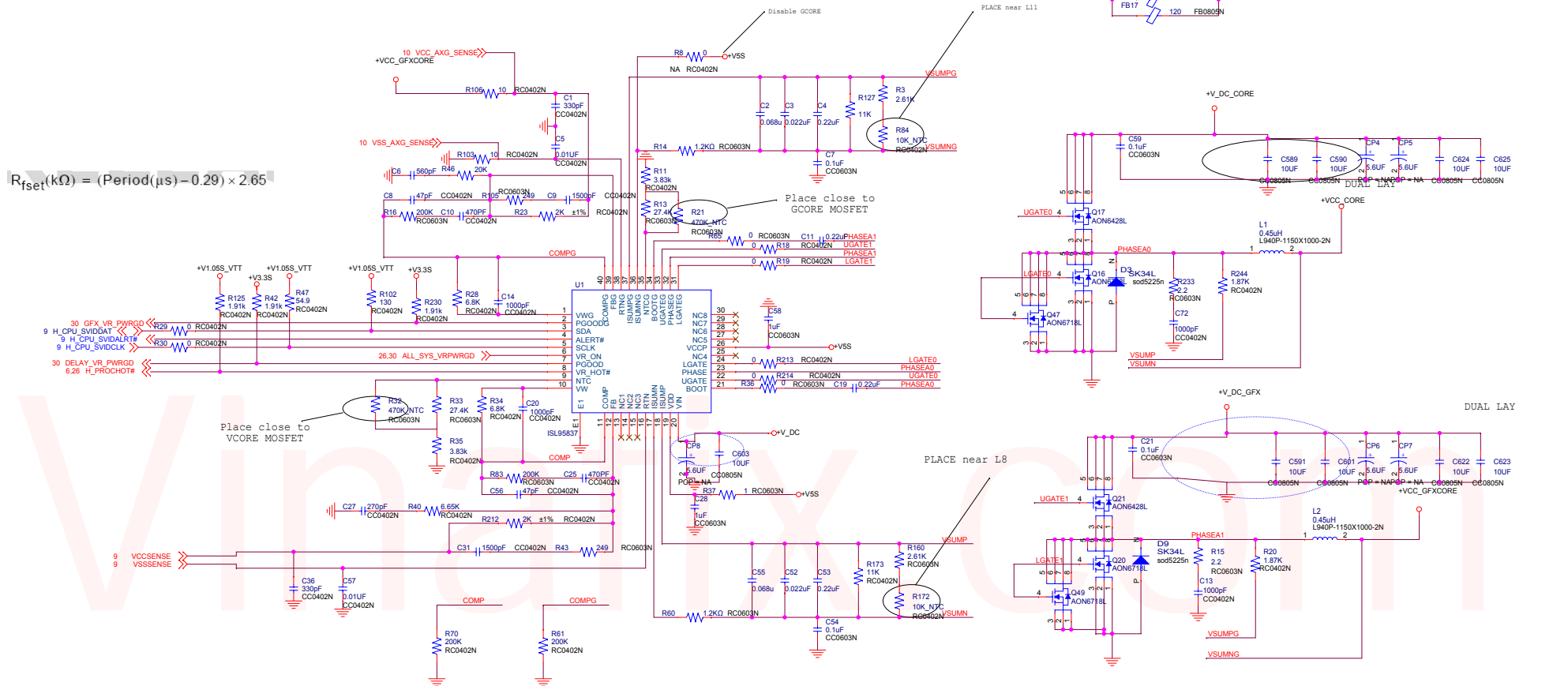
The ISL95870B V_{SET4} setpoint is written as Equation 24:

$$V_{SET4} = V_{REF} \cdot \left(1 + \frac{R_{SET1} + R_{SET2} + R_{SET3}}{R_{SET4}} \right) \quad (\text{EQ. 24})$$

<Core Design>

		Lengda Technology Ltd. 5th floor Block K, Xiamen Export Processing Zone, Haicang District, Xiamen, China, 361026	
		Title <Title> Size C Sheet Name Power_VCCSA Date: Monday, March 25, 2013 Sheet 35 of 38	
ENGINEER:	hvan	Rev	A

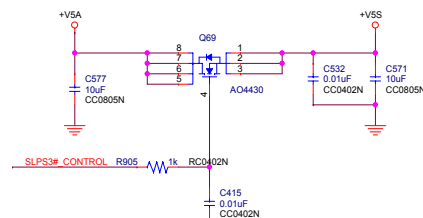
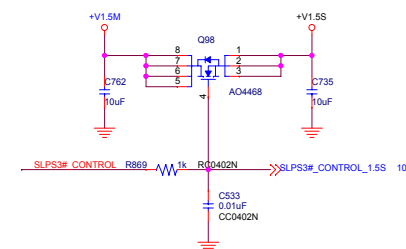
$$R_{fset}(k\Omega) = (\text{Period}(\mu s) - 0.29) \times 2.65$$



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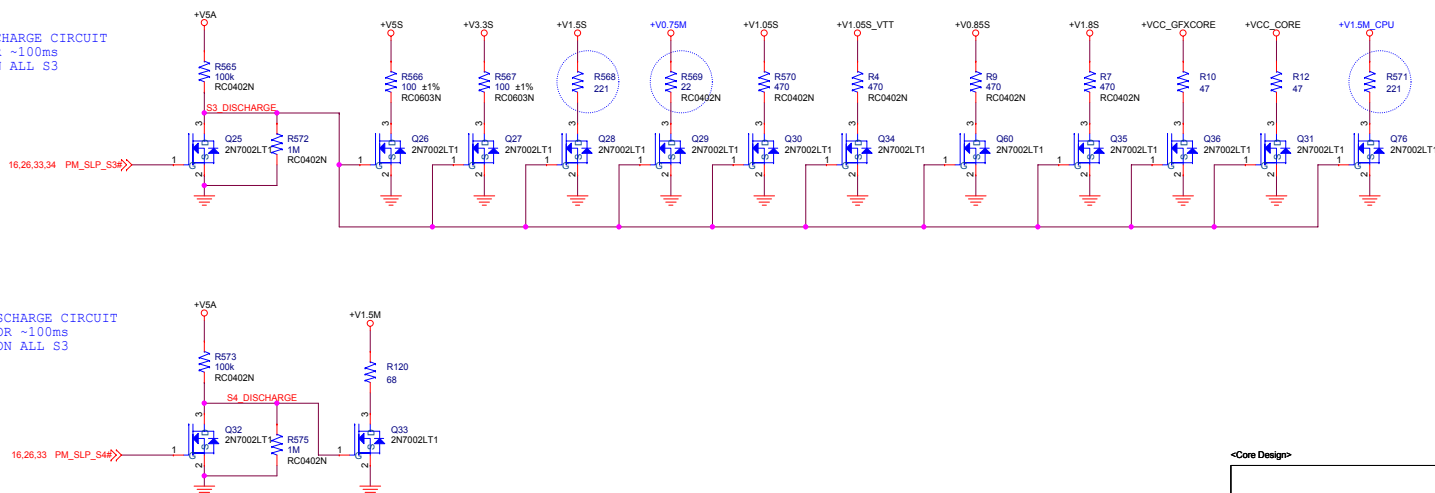
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		Title <Title>	Rev A
ENGINEER: Wain	Sheet Name	Power_Vcore	Date: Monday, March 25, 2013
		1Sheet	36 of 36

Power Discharge Circuit



Power Discharge Circuit

SLP S4# DISCHARGE CIRCUIT
DESIGNED FOR ~100ms
DISCHARGE ON ALL S3
RAILS.



Changelist V1.01

- 1、VCORE 和GFX电源增加磁珠
- 2、封装1206 10uf电容增加dualloy 1210封装极性电容
- 3、DD2结构干涉，挪到主板端
- 4、R17，R25，R67，R58丝印错误-----layout更改
- 5、MH7丝印改在BOT，TH区域标注有2个-----layout更改
- 6、增加touch pannel 电源控制TP_EN
- 7、LCD driver IC增加5V预留

<Core Design>		Lengda Technology Ltd.	
		20th Floor, Block A, Shenzhen Export Processing Zone, Futian District, Shenzhen, China, 518000	
Title <Title>		Rev A	
Revision		Change List	
Date: Monday, March 25, 2013		Time: 10:28 AM	